

January 29, 2002

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile     Reg. No. 19,572  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603

Subject:

**Divisional Patent Application of**

Serial No.: 08/239,575 5/6/94

SHYH-MING CHANG, JWO-HUEI JOU, YU-CHI  
LEE, DYI-CHUNG HU

COMPOSITE BUMP BONDING

**PRELIMINARY AMENDMENT**

Dear Sir:

This is a preliminary amendment for the above referenced Divisional Patent  
Application. Please amend the above identified application for patent as follows:

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States  
Postal Service as first class mail in an envelope addressed to: Commissioner of Patents  
and Trademarks, Washington, D.C. 20231, on January 30, 2002.

Stephen B. Ackerman, Reg. No. 37,761

Signature/Date



January 30, 2002

**PLEASE AMEND THE SPECIFICATION AS FOLLOWS:**

After the title, insert -- This is a division of Patent Application serial number 08/239,575, filing date 5/6/94, Composite Bump Bonding, assigned to the same assignee as the present invention.

**REMARKS**

A reference to the parent case has been added by Preliminary Amendment to this Divisional Patent Application.

The application is believed to be in condition for allowance. Allowance of the subject Patent Application is therefore respectfully requested.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'SB Ackerman', with a stylized flourish extending to the right.

STEPHEN B. ACKERMAN, REG. NO. 37,761

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